

B² A contact time of less than 10 seconds has generally been found to give insufficient coverage with silver coating and although the contact time may be longer than 10 minutes, no additional benefit has been found from a contact time of longer than 10 minutes. --

Please replace the paragraph beginning at page 18, line 9, with the following rewritten paragraph:

B³ -- The concentration of tarnish inhibitor in the solution comprising tarnish inhibitor will generally be from 0.0001 to 5% by weight, i.e., 0.001 to 50g/l. Preferably, the amount of tarnish inhibitor will be from 0.005 to 3% by weight, and most preferably from 0.01 to 2% by weight, or even below 1% by weight. --

Please replace the paragraph beginning at page 19, line 17, with the following rewritten paragraph:

B⁴ -- In a further aspect of the present invention there is provided a displacement metal plating process in which a relatively less electropositive base metal is plated with a relatively more electropositive coating metal by contact with an aqueous plating composition containing ions of the more electropositive metal, a complexing agent for such ions and a tarnish inhibitor for the more electropositive metal so as to form a coating of the more electropositive metal. --

Please replace the paragraph beginning at page 19, line 25, with the following rewritten paragraph:

B⁵ -- In this aspect of the invention there is also provided a new plating composition containing ions of a metal which can be displacement plated, a complexing agent for the ions, preferably present in higher than equimolar amounts as compared to the metal ion, and containing a tarnish inhibitor for the metal, and being substantially free of reducing agent capable of reducing the ions to the metal. --

Please replace the paragraph beginning at page 20, line 10, with the following rewritten paragraph:

B⁶ -- The plating composition used in this aspect of the invention may be an immersion plating composition based on any plating composition used in the PCB industry. --

Please replace the paragraph beginning at page 24, line 7, with the following rewritten paragraph:

B⁷ -- This invention has been found to provide considerable advantages in preventing tarnishing and conferring humidity resistance on the bare boards produced so that additional protection is provided between the bare board manufacture stage and the component-attachment stage. Solderability is found to be enhanced. --